Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

	Description
ML570G3	4 Processor Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	**Notes**	**Quantity of items included in product.**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB / PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		2
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials		0

containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
Philips type Driver	#2

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1	Battery - remove system cover, locate battery and remove by hand or small flat blade pry tool.
2	2.5CM capacitors – Remove Power supply(s), open with #2 Philips screwdriver, Remove the circuit board, pry the caps from the PCB with a flat blade screwdriver – see diagram
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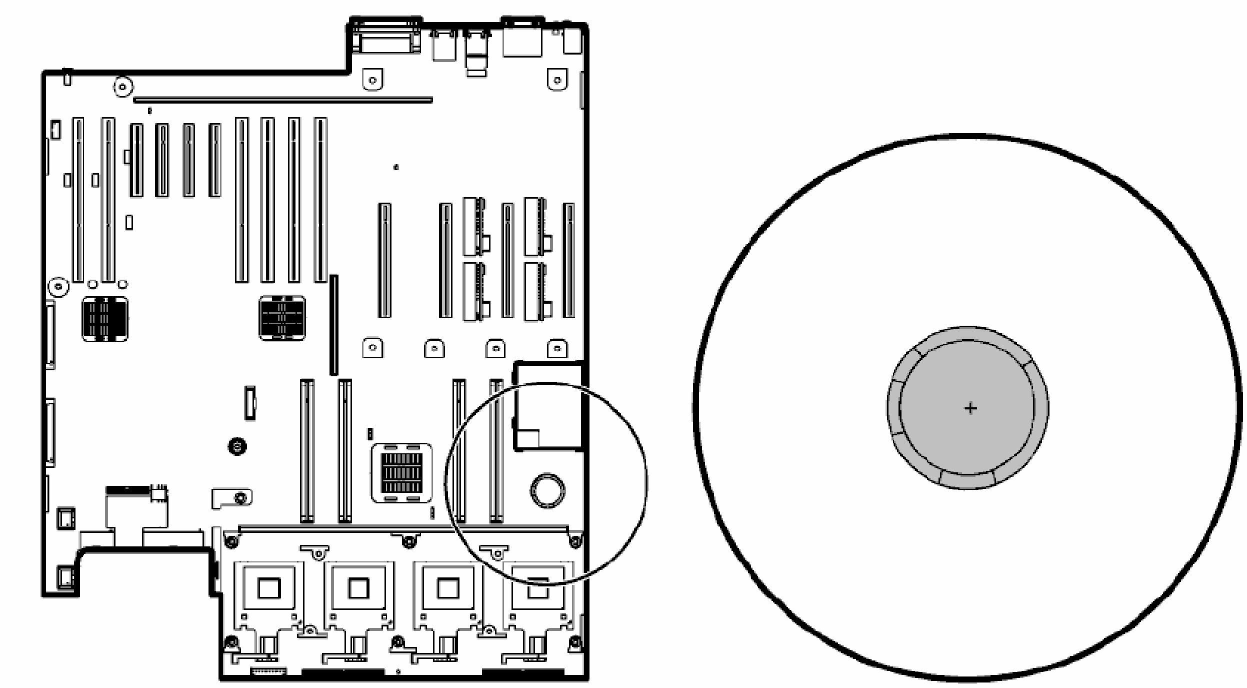
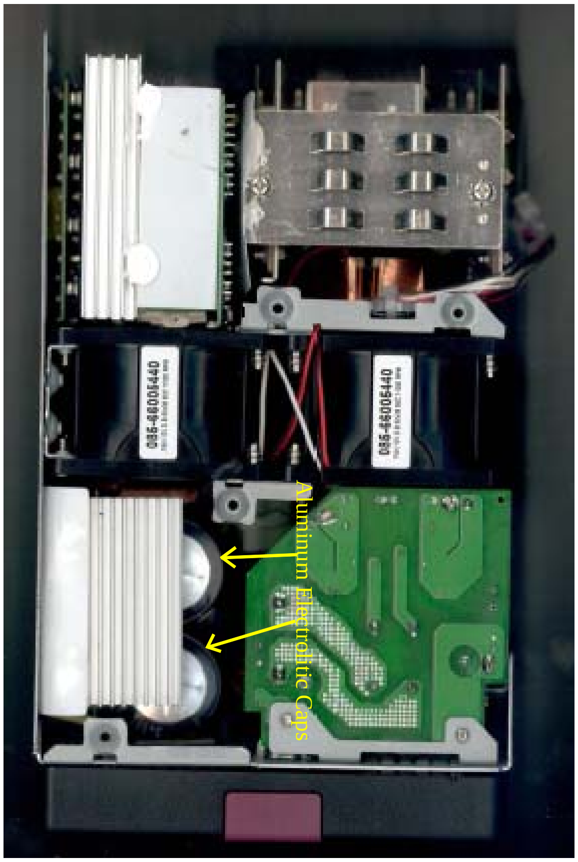
3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

Attachment 1 – Battery location

Attachment 2 – Capacitor locations




Aluminum Electrolitic Caps